ASSOCIATION CONNECT ELECTRONICS INDUSTRI	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute									ous Materia	ials and Mfg Information				
Supplier Infor	mation															
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*				
onsemi													2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*					
Product-Env-Ste	wards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorized Repre	esentative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-Env-Ste	wards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Reque	ster Item Number	r Item Number Mfr Item N					Effective Da	te Versi	ion I	Manufacturing Site		V	eight*	UOM	Unit Type	
		NCS37010DBRG ST		STB TSSOP			2023-06-08		I	PHG		7.	5.72	mg	Each	
Ianufacturin	g Proccess Informati	ion														
Termin	Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 M	SL Rating	Peak Pro	ak Process Body Temperature		e Max Tir	x Time at Peak Temper		nture Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy		3		260		С	30 seco		second	s 3			
comments																
TTENTION: M	SL 3 Rated item requires	Bake and I	Ory Pack (after	r electrical test)												
or more informa	ation regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.34	mg	Supplier	Silicon (Si)	7440-21-3		7.34	mg
Die Attach	4.13	mg		Epoxy resin	proprietary data		0.413	mg
			Supplier	Ethylene dimethacrylate	97-90-5		0.2065	mg
			Supplier	Silver (Ag)	7440-22-4		3.304	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2065	mg
Lead Frame	26.12	mg	Supplier	Zinc (Zn)	7440-66-6		0.0261	mg
			Supplier	Iron (Fe)	7439-89-6		0.6008	mg
			Supplier	Copper (Cu)	7440-50-8		25.467	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0261	mg
Mold Compound-Black	37.4	mg		Epoxy resin	proprietary data		1.87	mg
			Supplier	Phenolic Resin	Proprietary Data		0.748	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.935	mg
			Supplier	Carbon Black (C)	1333-86-4		0.187	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.66	mg
Plating	0.19		Supplier	Palladium (Pd)	7440-05-3		0.0112	mg
			В	Nickel (Ni)	7440-02-0		0.1677	mg
			Supplier	Gold (Au)	7440-57-5		0.0112	mg
Wire Bond - Au	0.54	mg	Supplier	Gold (Au)	7440-57-5		0.54	mg